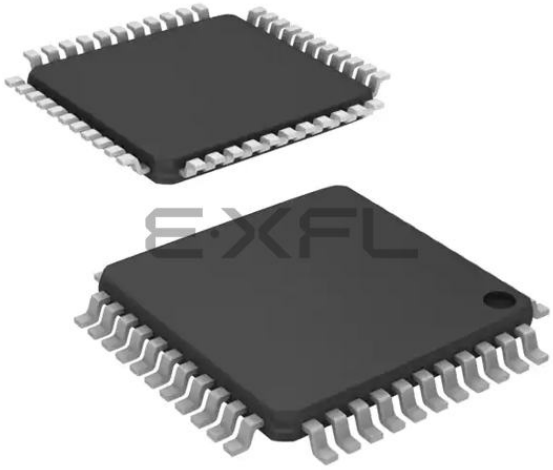

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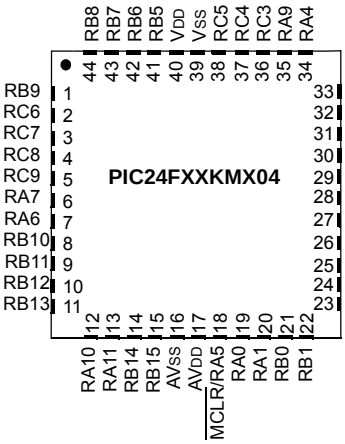
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	37
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5V
Data Converters	A/D 22x10b/12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv08km204t-i-pt

Pin Diagrams (Continued)

44-Pin TQFP/QFN(1)

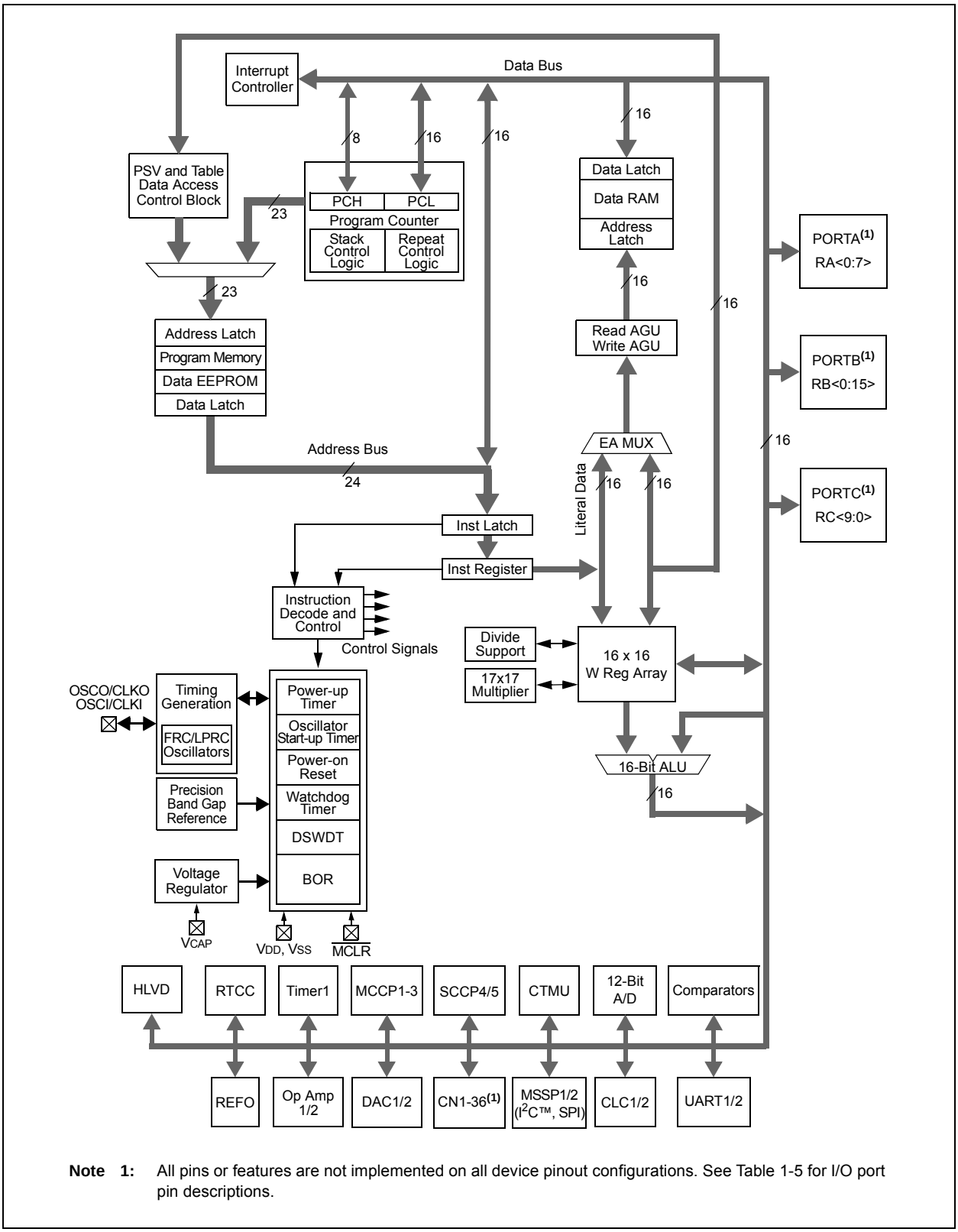


Pin	Pin Features	
	PIC24FXXKMX04	PIC24FVXXKMX04
1	AN21/SDA1/T1CK/U1RTS/U1BCLK/IC2/ /CLC1O/CTED4/CN21/RB9	
2	U1RX/ /CN18/RC6	
3	U1TX/ /CN17/RC7	
4	/CN20/RC8	
5	IC4/OC2F/CTED7/CN19/RC9	
6	IC1/ / /CTED3/CN9/RA7	
7	/OC1A/CTED1/INT2/CN8/RA6	VCAP or VDDCORE
8	PGED2/SDI1/OC1C/CTED11/CN16/RB10	
9	PGEC2/SCK1/OC2A/CTED9/CN15/RB11	
10	/AN12/HLVDIN/ /CTED2/ CN14/RB12	/AN12/HLVDIN/ /CTED2/INT2/ CN14/RB12
11	/ /AN11/SDO1/OC1D/CTPLS/CN13/RB13	
12	/ /CN35/RA10	
13	/ /CTED8/CN36/RA11	
14	/CVREF/ / /AN10/ / /C1OUT/OCFA/CTED5/INT1/CN12/ RB14	
15	/ /AN9/ /REFO/SS1/TCKIA/CTED6/CN11/RB15	
16	AVSS	
17	AVDD	
18	MCLR/VPP/RA5	
19	CVREF+/VREF+/ /AN0/ /CN2/ RA0	CVREF+/VREF+/ /AN0/ / CTED1/CN2/RA0
20	CVREF-/VREF-/AN1/CN3/RA1	
21	PGED1/AN2/CTCMP/ULPWU/C1IND/ / / /CN4/RB0	
22	PGEC1/ / /AN3/C1INC/ / /CTED12/CN5//RB1	
23	/ /AN4/C1INB/ / /TCKIB/CTED13/CN6/RB2	
24	/AN5/C1INA/ / /CN7/RB3	
25	AN6/CN32/RC0	
26	AN7/CN31/RC1	
27	AN8/CN10/RC2	
28	VDD	
29	VSS	
30	OSCI/CLKI/AN13/CN30/RA2	
31	OSCO/CLKO/AN14/CN29/RA3	
32	OCFB/CN33/RA8	
33	SOSCI/AN15/ / /CN1/RB4	
34	SOSCO/SCLKI/AN16/PWRLCLK/ /CN0/RA4	
35	/CN34/RA9	
36	/CN28/RC3	
37	/CN25/RC4	
38	/CN26/RC5	
39	VSS	
40	VDD	
41	PGED3/AN17/ASDA1/OC1E/CLCINA/CN27/RB5	
42	PGEC3/AN18/ASCL1/OC1F/CLCINB/CN24/RB6	
43	AN19/INT0/CN23/RB7	AN19/ /OC1A/INT0/CN23/RB7
44	AN20/SCL1/U1CTS/C3OUT/OC1B/CTED10/CN22/RB8	

Legend: Values in indicate pin function differences between PIC24F(V)XXKM202 and PIC24F(V)XXKM102 devices.

Note 1: Exposed pad on underside of device is connected to VSS.

FIGURE 1-1: PIC24FXXXXX FAMILY GENERAL BLOCK DIAGRAMS



Note 1: All pins or features are not implemented on all device pinout configurations. See Table 1-5 for I/O port pin descriptions.

3.0 CPU

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the CPU, refer to the *"PIC24F Family Reference Manual"*, **"CPU"** (DS39703).

The PIC24F CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set and a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M instructions of user program memory space. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `REPEAT` instructions, which are interruptible at any point.

PIC24F devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can act as a data, address or address offset register. The 16th working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

The upper 32 Kbytes of the Data Space (DS) memory map can optionally be mapped into program space at any 16K word boundary of either program memory or data EEPROM memory, defined by the 8-bit Program Space Visibility Page Address (PSVPAG) register. The program to Data Space mapping feature lets any instruction access program space as if it were Data Space.

The Instruction Set Architecture (ISA) has been significantly enhanced beyond that of the PIC18, but maintains an acceptable level of backward compatibility. All PIC18 instructions and addressing modes are supported, either directly, or through simple macros. Many of the ISA enhancements have been driven by compiler efficiency needs.

The core supports Inherent (no operand), Relative, Literal, Memory Direct and three groups of addressing modes. All modes support Register Direct and various Register Indirect modes. Each group offers up to seven addressing modes. Instructions are associated with predefined addressing modes depending upon their functional requirements.

For most instructions, the core is capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing trinary operations (i.e., A + B = C) to be executed in a single cycle.

A high-speed, 17-bit by 17-bit multiplier has been included to significantly enhance the core arithmetic capability and throughput. The multiplier supports Signed, Unsigned and Mixed mode, 16-bit by 16-bit or 8-bit by 8-bit integer multiplication. All multiply instructions execute in a single cycle.

The 16-bit ALU has been enhanced with integer divide assist hardware that supports an iterative non-restoring divide algorithm. It operates in conjunction with the `REPEAT` instruction looping mechanism and a selection of iterative divide instructions to support 32-bit (or 16-bit), divided by 16-bit integer signed and unsigned division. All divide operations require 19 cycles to complete but are interruptible at any cycle boundary.

The PIC24F has a vectored exception scheme with up to eight sources of non-maskable traps and up to 118 interrupt sources. Each interrupt source can be assigned to one of seven priority levels.

A block diagram of the CPU is illustrated in Figure 3-1.

3.1 Programmer's Model

Figure 3-2 displays the programmer's model for the PIC24F. All registers in the programmer's model are memory mapped and can be manipulated directly by instructions.

Table 3-1 provides a description of each register. All registers associated with the programmer's model are memory mapped.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® devices and improve Data Space memory usage efficiency, the PIC24F instruction set supports both word and byte operations. As a consequence of byte accessibility, all EA calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word, which contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, the data memory and the registers are organized as two parallel, byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register, which matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed; if it occurred on a write, the instruction will be executed, but the write will not occur. In either case, a trap is then executed, allowing the system and/or user to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow the users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions operate only on words.

4.2.3 NEAR DATA SPACE

The 8-Kbyte area between 0000h and 1FFFh is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. The remainder of the Data Space is addressable indirectly. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing (MDA) with a 16-bit address field. For PIC24FV16KM204 family devices, the entire implemented data memory lies in Near Data Space (NDS).

4.2.4 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0000h to 07FFh, are primarily occupied with Special Function Registers (SFRs). These are used by the PIC24F core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by that module. Much of the SFR space contains unused addresses; these are read as '0'. The SFR space, where the SFRs are actually implemented, is provided in Table 4-2. Each implemented area indicates a 32-byte region where at least one address is implemented as an SFR. A complete listing of implemented SFRs, including their addresses, is provided in Table 4-3 through Table 4-26.

TABLE 4-2: IMPLEMENTED REGIONS OF SFR DATA SPACE

	SFR Space Address							
	xx00	**xx20**	**xx40**	**xx60**	**xx80**	**xxA0**	**xxC0**	**xxE0**
000h	Core			ICN	Interrupts			—
100h	Timers	CLC	MCCP/SCCP					
200h	MSSP	UART	Op Amp	DAC	—	—	I/O	
300h	A/D/CMTU				—	—	—	—
400h	—	—	—	—	—	—	—	ANSEL
500h	—	—	—	—	—	—	—	—
600h	—	RTCC/Comp	—	Band Gap	—			
700h	—	—	System/ HLVD	NVM/PMD	—	—	—	—

Legend: — = No implemented SFRs in this block.

REGISTER 8-10: IFS5: INTERRUPT FLAG STATUS REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	ULPWUIF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as '0'

bit 0 **ULPWUIF:** Ultra Low-Power Wake-up Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 8-11: IFS6: INTERRUPT FLAG STATUS REGISTER 6

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0, HS
—	—	—	—	—	—	CLC2IF	CLC1IF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as '0'

bit 1 **CLC2IF:** Configurable Logic Cell 2 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **CLC1IF:** Configurable Logic Cell 1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 9-3: OSCTUN: FRC OSCILLATOR TUNE REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN5(1)	TUN4(1)	TUN3(1)	TUN2(1)	TUN1(1)	TUN0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

011111 = Maximum frequency deviation
011110
•
•
•
000001
000000 = Center frequency, oscillator is running at factory calibrated frequency
111111
•
•
•
100001
100000 = Minimum frequency deviation

Note 1: Increments or decrements of TUN<5:0> may not change the FRC frequency in equal steps over the FRC tuning range and may not be monotonic.

REGISTER 9-4: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROEN:** Reference Oscillator Output Enable bit
1 = Reference Oscillator is enabled on the REFO pin
0 = Reference Oscillator is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Output Stop in Sleep bit
1 = Reference Oscillator continues to run in Sleep
0 = Reference Oscillator is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Primary Oscillator is used as the base clock(1)
0 = System clock is used as the base clock; base clock reflects any clock switching of the device

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divisor Select bits
1111 = Base clock value divided by 32,768
1110 = Base clock value divided by 16,384
1101 = Base clock value divided by 8,192
1100 = Base clock value divided by 4,096
1011 = Base clock value divided by 2,048
1010 = Base clock value divided by 1,024
1001 = Base clock value divided by 512
1000 = Base clock value divided by 256
0111 = Base clock value divided by 128
0110 = Base clock value divided by 64
0101 = Base clock value divided by 32
0100 = Base clock value divided by 16
0011 = Base clock value divided by 8
0010 = Base clock value divided by 4
0001 = Base clock value divided by 2
0000 = Base clock value

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The crystal oscillator must be enabled using the FOSC<2:0> bits; the crystal maintains the operation in Sleep mode.

10.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Power-Saving Features with VBAT"** (DS30622).

This FRM describes some features which are not implemented in this device. Sections related to the VBAT pin and Deep Sleep do not apply to the PIC24FV16KM204 family.

The PIC24FV16KM204 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation.

The 'C' syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode includes these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The I/O pin directions and states are frozen.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT or RTCC with LPRC as the clock source is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items, such as the Input Change Notification on the I/O ports or peripherals that use an External Clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled
- On any form of device Reset
- On a WDT time-out

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: 'C' POWER-SAVING ENTRY

```
Sleep();              //Put the device into Sleep mode
Idle();               //Put the device into Idle mode
```

REGISTER 13-4: CCPxCON2H: CCPx CONTROL 2 HIGH REGISTERS

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OENSYNC	—	OCFEN(1)	OCEEN(1)	OCDEN(1)	OCCEN(1)	OCBEN(1)	OCAEN
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ICGSM1	ICGSM0	—	AUXOUT1	AUXOUT0	ICS2	ICS1	ICS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OENSYNC:** Output Enable Synchronization bit
1 = Update by output enable bits occurs on the next Time Base Reset or rollover
0 = Update by output enable bits occurs immediately

bit 14 **Unimplemented:** Read as '0'

bit 13-8 **OC<F:A>EN:** Output Enable/Steering Control bits(1)
1 = OCx pin is controlled by the CCPx module and produces an output compare or PWM signal
0 = OCx pin is not controlled by the CCPx module; the pin is available to the port logic or another peripheral multiplexed on the pin

bit 7-6 **ICGSM<1:0>:** Input Capture Gating Source Mode Control bits
11 = Reserved
10 = One-Shot mode: Falling edge from gating source disables future capture events (ICDIS = 1)
01 = One-Shot mode: Rising edge from gating source enables future capture events (ICDIS = 0)
00 = Level-Sensitive mode: A high level from gating source will enable future capture events; a low level will disable future capture events

bit 5 **Unimplemented:** Read as '0'

bit 4-3 **AUXOUT<1:0>:** Auxiliary Output Signal on Event Selection bits
11 = Input capture or output compare event; no signal in Timer mode
10 = Signal output is defined by module operating mode (see Table 13-5)
01 = Time base rollover event (all modes)
00 = Disabled

bit 2-0 **ICS<2:0>:** Input Capture Source Select bits
111 = Unused
110 = CLC2 output
101 = CLC1 output
100 = Unused
011 = Comparator 3 output
010 = Comparator 2 output
001 = Comparator 1 output
000 = Input Capture x (ICx) I/O pin

Note 1: OCFEN through OCBEN (bits<13:9>) are implemented in MCCPx modules only.

REGISTER 14-7: SSPxCON3: MSSPx CONTROL REGISTER 3 (I^2C™ MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ACKTIM(1)	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **ACKTIM:** Acknowledge Time Status bit(1)
1 = Indicates the I^2C bus is in an Acknowledge sequence, set on the 8th falling edge of the SCLx clock
0 = Not an Acknowledge sequence, cleared on the 9th rising edge of the SCLx clock

bit 6 **PCIE**: Stop Condition Interrupt Enable bit
1 = Enables interrupt on detection of a Stop condition
0 = Stop detection interrupts are disabled(2)

bit 5 **SCIE**: Start Condition Interrupt Enable bit
1 = Enables interrupt on detection of a Start or Restart condition
0 = Start detection interrupts are disabled(2)

bit 4 **BOEN:** Buffer Overwrite Enable bit
I^2C Master mode:
This bit is ignored.
I^2C Slave mode:
1 = SSPxBUF is updated and an $\overline{ACK}$ is generated for a received address/data byte, ignoring the state of the SSPOV bit only if the BF bit = 0
0 = SSPxBUF is only updated when SSPOV is clear

bit 3 **SDAHT:** SDAx Hold Time Selection bit
1 = Minimum of 300 ns hold time on SDAx after the falling edge of SCLx
0 = Minimum of 100 ns hold time on SDAx after the falling edge of SCLx

bit 2 **SBCDE:** Slave Mode Bus Collision Detect Enable bit (Slave mode only)
1 = Enables slave bus collision interrupts
0 = Slave bus collision interrupts are disabled

bit 1 **AHEN:** Address Hold Enable bit (Slave mode only)
1 = Following the 8th falling edge of SCLx for a matching received address byte; CKP bit of the SSPxCON1 register will be cleared and SCLx will be held low
0 = Address holding is disabled

bit 0 **DHEN:** Data Hold Enable bit (Slave mode only)
1 = Following the 8th falling edge of SCLx for a received data byte; slave hardware clears the CKP bit of the SSPxCON1 register and SCLx is held low
0 = Data holding is disabled

Note 1: This bit has no effect in Slave modes for which Start and Stop condition detection is explicitly listed as enabled.
2: The ACKTIM status bit is active only when the AHEN bit or DHEN bit is set.

REGISTER 16-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1) (CONTINUED)

bit 7-0 **CAL<7:0>:** RTC Drift Calibration bits

01111111 = Maximum positive adjustment; adds 508 RTC clock pulses every one minute
.
.
.
00000001 = Minimum positive adjustment; adds 4 RTC clock pulses every one minute
00000000 = No adjustment
11111111 = Minimum negative adjustment; subtracts 4 RTC clock pulses every one minute
.
.
.
10000000 = Maximum negative adjustment; subtracts 512 RTC clock pulses every one minute

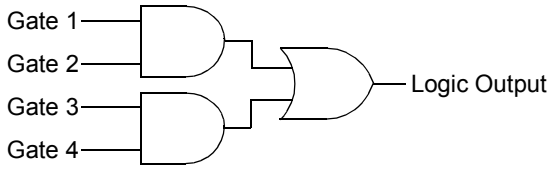
Note 1: The RCFGCAL register is only affected by a POR.

2: A write to the RTCEN bit is only allowed when RTCWREN = 1.

3: This bit is read-only; it is cleared to '0' on a write to the lower half of the MINSEC register.

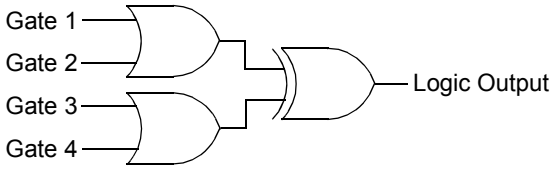
FIGURE 17-2: CLCx LOGIC FUNCTION COMBINATORIAL OPTIONS

AND – OR



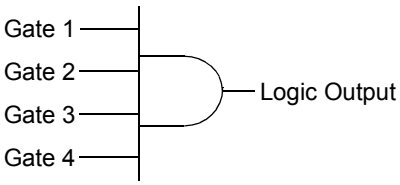
MODE<2:0> = 000

OR – XOR



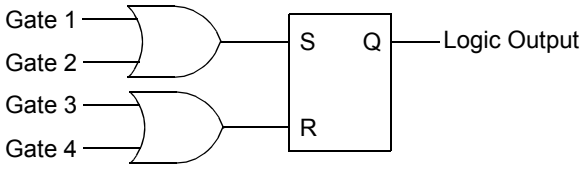
MODE<2:0> = 001

4-Input AND



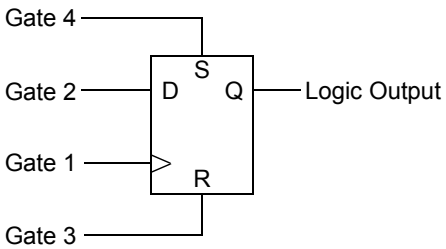
MODE<2:0> = 010

S-R Latch



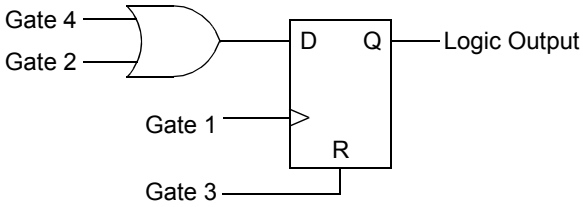
MODE<2:0> = 011

1-Input D Flip-Flop with S and R



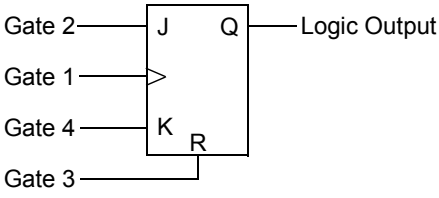
MODE<2:0> = 100

2-Input D Flip-Flop with R



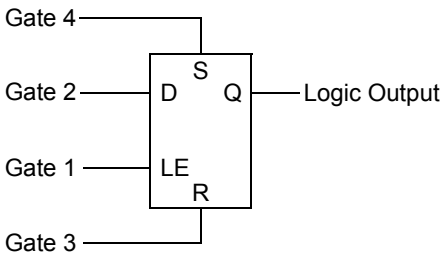
MODE<2:0> = 101

J-K Flip-Flop with R



MODE<2:0> = 110

1-Input Transparent Latch with S and R



MODE<2:0> = 111

REGISTER 22-1: CMxCON: COMPARATOR x CONTROL REGISTERS (CONTINUED)

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator x Channel Select bits
11 = Inverting input of the comparator connects to BGBUF1(1)
10 = Inverting input of the comparator connects to the CxIND pin
01 = Inverting input of the comparator connects to the CxINC pin
00 = Inverting input of the comparator connects to the CxINB pin

Note 1: BGBUF1 voltage is configured by BUFREF1<1:0> (BUFCON0<1:0>).

2: If the EVPOL<1:0> bits are set to a value other than '00', the first interrupt generated will occur on any transition of COUT. Subsequent interrupts will occur based on the EVPOLx bits setting.

REGISTER 22-2: CMSTAT: COMPARATOR MODULE STATUS REGISTER

R/W-0	U-0	U-0	U-0	U-0	R-0, HSC	R-0, HSC	R-0, HSC
CMIDL	—	—	—	—	C3EVT(1)	C2EVT(1)	C1EVT
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R-0, HSC	R-0, HSC	R-0, HSC
—	—	—	—	—	C3OUT(1)	C2OUT(1)	C1OUT
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CMIDL:** Comparator x Stop in Idle Mode bit
1 = Comparator interrupts are disabled in Idle mode; enabled comparators remain operational
0 = Continues operation of all enabled comparators in Idle mode

bit 14-11 **Unimplemented:** Read as '0'

bit 10 **C3EVT:** Comparator 3 Event Status bit (read-only)(1)
Shows the current event status of Comparator 3 (CM3CON<9>).

bit 9 **C2EVT:** Comparator 2 Event Status bit (read-only)(1)
Shows the current event status of Comparator 2 (CM2CON<9>).

bit 8 **C1EVT:** Comparator 1 Event Status bit (read-only)
Shows the current event status of Comparator 1 (CM1CON<9>).

bit 7-3 **Unimplemented:** Read as '0'

bit 2 **C3OUT:** Comparator 3 Output Status bit (read-only)(1)
Shows the current output of Comparator 3 (CM3CON<8>).

bit 1 **C2OUT:** Comparator 2 Output Status bit (read-only)(1)
Shows the current output of Comparator 2 (CM2CON<8>).

bit 0 **C1OUT:** Comparator 1 Output Status bit (read-only)
Shows the current output of Comparator 1 (CM1CON<8>).

Note 1: Comparator 2 and Comparator 3 are only available on PIC24F(V)16KM2XX devices.

REGISTER 25-2: FGS: GENERAL SEGMENT CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/C-1	R/C-1
—	—	—	—	—	—	GCP	GWRP
bit 7							bit 0

Legend:			
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **GCP:** General Segment Code Flash Code Protection bit
1 = No protection
0 = Standard security is enabled

bit 0 **GWRP:** General Segment Code Flash Write Protection bit
1 = General Segment may be written
0 = General Segment is write-protected

REGISTER 25-3: FOSCSEL: OSCILLATOR SELECTION CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	U-0	U-0	R/P-1	R/P-1	R/P-1
IESO	LPRCSEL	SOSCSRC	—	—	FNOSC2	FNOSC1	FNOSC0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IESO:** Internal External Switchover bit
1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **LPRCSEL:** Internal LPRC Oscillator Power Select bit
1 = High-Power/High-Accuracy mode
0 = Low-Power/Low-Accuracy mode

bit 5 **SOSCSRC:** Secondary Oscillator Clock Source Configuration bit
1 = SOSC analog crystal function is available on the SOSCI/SOSCO pins
0 = SOSC crystal is disabled; digital SCLKI function is selected on the SOSCO pin

bit 4-3 **Unimplemented:** Read as '0'

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits
000 = Fast RC Oscillator (FRC)
001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCDIV+PLL)
010 = Primary Oscillator (XT, HS, EC)
011 = Primary Oscillator with PLL module (HS+PLL, EC+PLL)
100 = Secondary Oscillator (SOSC)
101 = Low-Power RC Oscillator (LPRC)
110 = 500 kHz Low-Power FRC Oscillator with Divide-by-N (LPFRCDIV)
111 = 8 MHz FRC Oscillator with Divide-by-N (FRCDIV)

25.4 Program Verification and Code Protection

For all devices in the PIC24FXXXXX family, code protection for the Boot Segment is controlled by the Configuration bit, BSS0, and the General Segment by the Configuration bit, GCP. These bits inhibit external reads and writes to the program memory space This has no direct effect in normal execution mode.

Write protection is controlled by bit, BWRP, for the Boot Segment and bit, GWRP, for the General Segment in the Configuration Word. When these bits are programmed to '0', internal write and erase operations to program memory are blocked.

25.5 In-Circuit Serial Programming

PIC24FXXXXX family microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock (PGECx) and data (PGEDx), and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

25.6 In-Circuit Debugger

When MPLAB® ICD 3, MPLAB REAL ICE™ or PICkit™ 3 is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx and PGEDx pins.

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{MCLR}$, V_{DD}, V_{SS}, PGECx, PGEDx and the pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins.

TABLE 27-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical(1)**	**Max**	**Units**	**Conditions**	
Module Differential Current (ΔI_{PD})(3)						
DC71	PIC24FV16KMXXX	0.50	—	µA	2.0V	Watchdog Timer Current: ΔWDT
		0.70	1.5	µA	5.0V	
	PIC24F16KMXXX	0.50	—	µA	1.8V	
		0.70	1.5	µA	3.3V	
DC72	PIC24FV16KMXXX	0.80	—	µA	2.0V	32 kHz Crystal with RTCC, DSWDT or Timer1: ΔSOSC (SOSCSEL = 0)
		1.50	2.0	µA	5.0V	
	PIC24F16KMXXX	0.70	—	µA	1.8V	
		1.0	1.5	µA	3.3V	
DC75	PIC24FV16KMXXX	5.4	—	µA	2.0V	ΔHLVD
		8.1	14.0	µA	5.0V	
	PIC24F16KMXXX	4.9	—	µA	1.8V	
		7.5	14.0	µA	3.3V	
DC76	PIC24FV16KMXXX	5.6	—	µA	2.0V	ΔBOR
		6.5	11.2	µA	5.0V	
	PIC24F16KMXXX	5.6	—	µA	1.8V	
		6.0	11.2	µA	3.3V	
DC78	PIC24FV16KMXXX	0.03	—	µA	2.0V	Low-Power BOR: ΔLPBOR
		0.05	0.3	µA	5.0V	
	PIC24F16KMXXX	0.03	—	µA	1.8V	
		0.05	0.3	µA	3.3V	

Legend: Unshaded rows represent PIC24F16KMXXX devices and shaded rows represent PIC24FV16KMXXX devices.

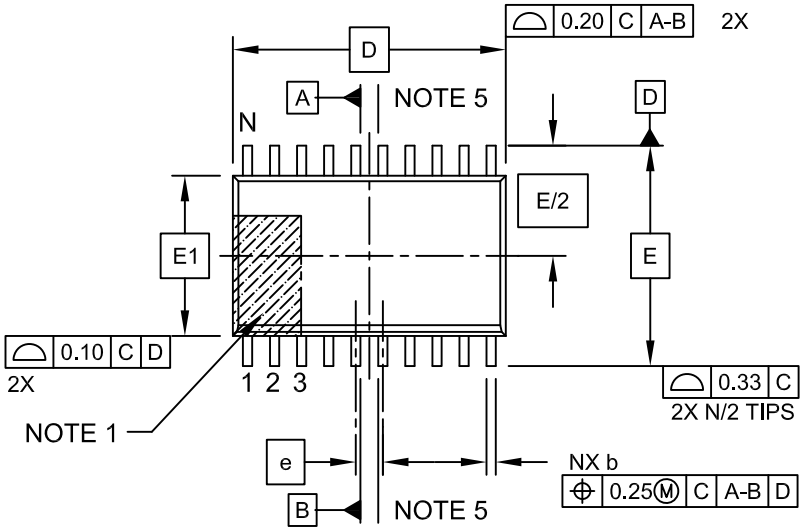
Note 1: Data in the Typical column is at 3.3V, +25°C (PIC24F16KMXXX) or 5.0V, +25°C (PIC24FV16KMXXX) unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as outputs and set low. PMSLP is set to '0' and WDT, etc., are all switched off.

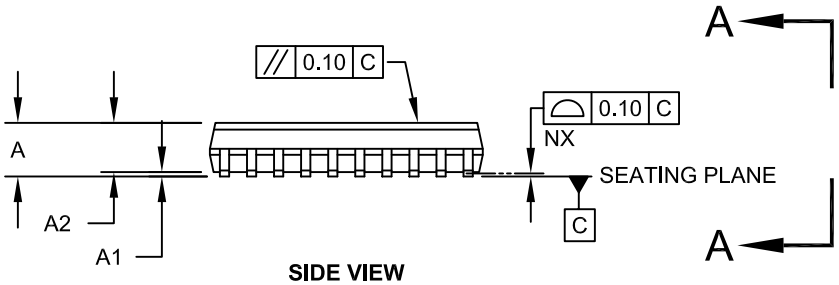
3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

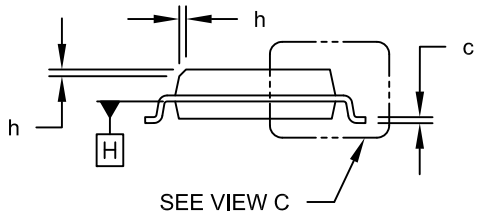
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

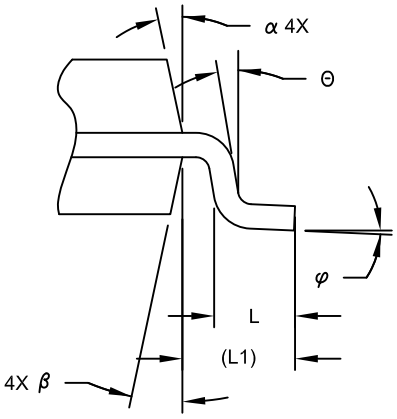


VIEW A-A

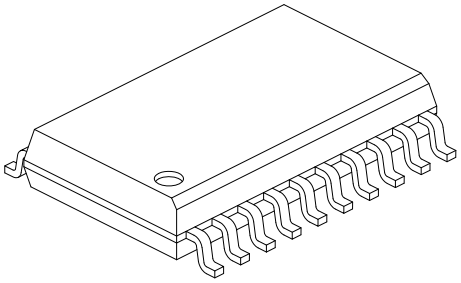
Microchip Technology Drawing C04-094C Sheet 1 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

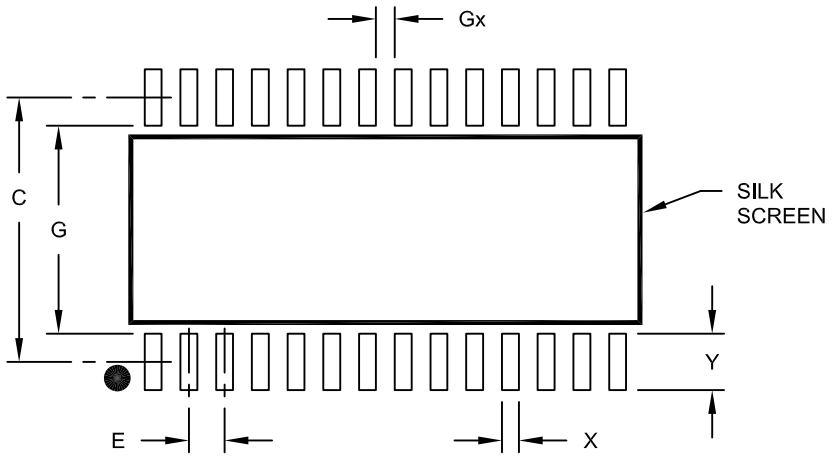
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

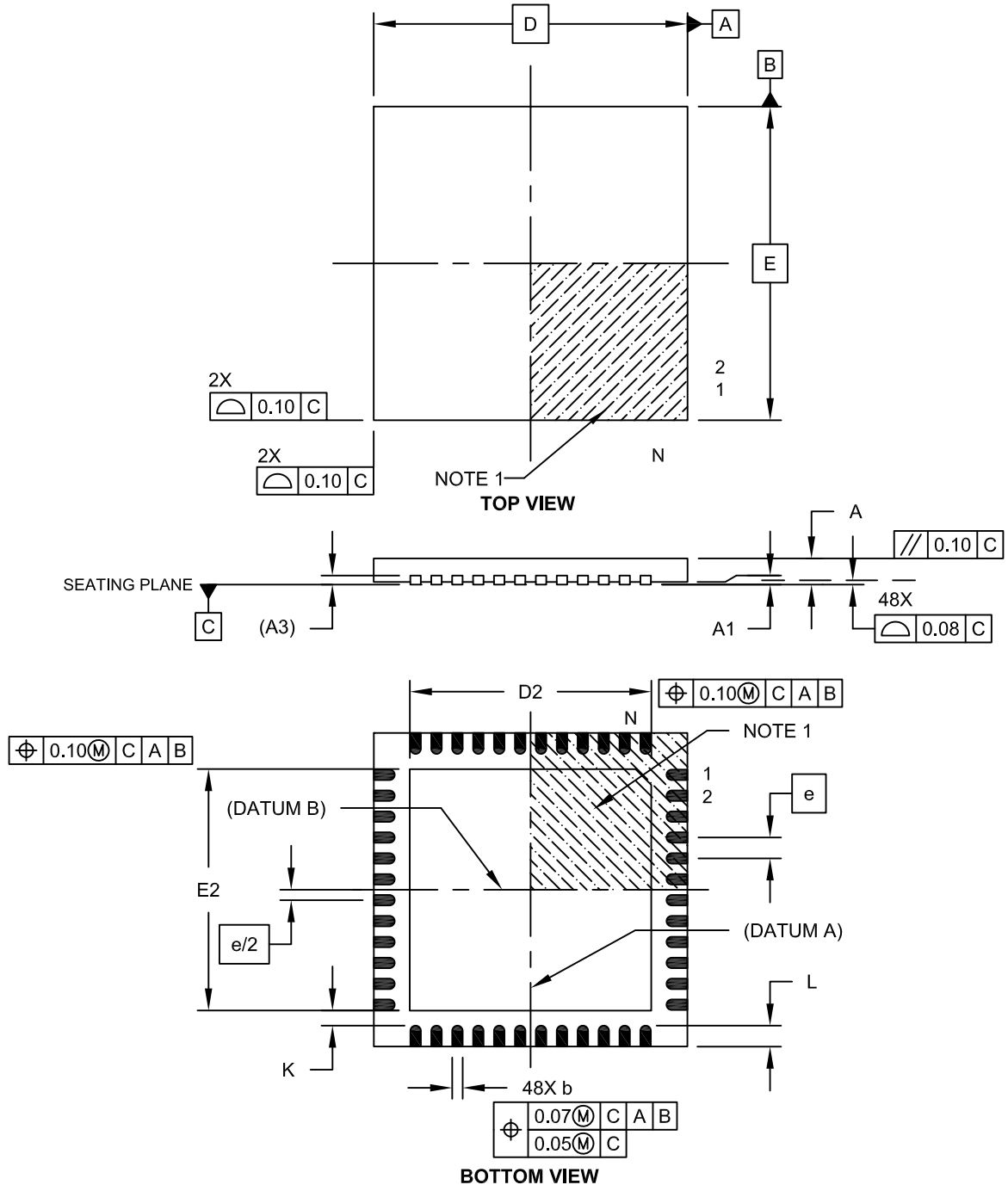
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-153A Sheet 1 of 2